



HITHERM[™] Thermal Interface Materials

eGRAF[®]

Advanced Thermal Management Solutions

eGRAF[®] HITHERM[™] high performance thermal interface materials (TIMs) are designed for long life, mission critical applications with extreme heat cycles. HITHERM[™] TIMs are made of flexible graphite specifically engineered for demanding lighting, computing and power electronics applications.

- Consistent, reliable thermal performance enabling zero maintenance applications
- Will not flow or pump out under any thermal extremes, thermal cycles, or part orientation
- Assembly-ready foil form factor eliminates dispensing and cleaning processes
- "NASA certified" minimal outgassing prevents fouling of optics in lighting applications



Chip on Board LED Engines



Assembly-ready LED TIM parts now available

Characteristic	HT-1200	HT-2500	HT-C3200
Typical Applications	Chip on Board LED devices Small light engines	Telecommunications CPU/GPU thermal interface	Motor drives Power inverters
Minimum Clamping Force	180 kPa ● 30 PSI	90 kPa ● 15 PSI	300 kPa ● 45 PSI
Surface Compensation @ 700 kPa (100 PSI)	Up to 0.021 mm roughness Near flat surface	Up to 0.015 mm roughness Near flat surface	Up to 0.030 mm roughness Up to 0.1 mm flatness compensation
Material Compression @ 700 kPa (100 PSI)	4% of starting thickness	6% of starting thickness	70% of starting thickness
Outgassing Losses TML ^[1]	<0.1%	1.3%	<0.1%

Notes:

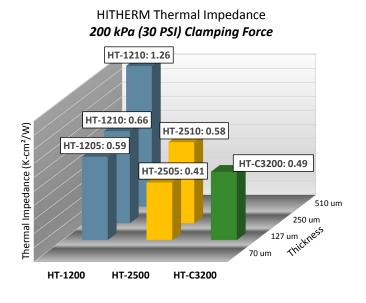
[1] E595 total mass loss (TML) test results of bare HITHERM[™] TIMs

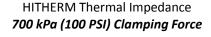
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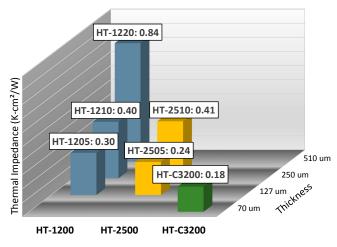
Material Options	Details	
Coating Options	Laminated with plastics or adhesives to meet dielectric and manufacturing requirements.	
Thickness Range	From 0.127 to 0.51mm (varies depending on grade). See HITHERM™ Technical Data Sheets 318 and 319 for more details.	
Certifications	Meets RoHS certifications.	
Flammability Rating	UL94V-0	

Material Performance

When determining which grade and thickness of HITHERM[™] TIMs will work for your application, the effective thermal impedance is the critical factor. The thermal impedance is the combination of the thermal resistance at the contact surfaces and the bulk resistance of the TIM.







Our global team of Applications Engineers are knowledgeable about graphite and applications spanning multiple industries. These include metallurgical casting, electronics, chemical, nuclear, defense/aerospace, solar, LED, semiconductor, and other high temperature processes.

Regardless of your product design phase (concept, prototyping, or mass production), we offer technical answers to some of your most challenging problems with a fast response time.



Please contact a GrafTech Applications Engineer today at applicationsengineering@graftech.com

Redefining limits

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